

Symposium on Reliability for Electronics and Photonics Packaging

Reliability, Failure Modes and Testing for Integration of Electronics and Photonics (SiPho)

Theme: Reliability for Advanced Semiconductor Packaging

November 7-8, 2024, hosted at Purdue University, West Lafayette, Indiana USA

Note: REPP-2024 is planned as a hybrid event, with both in-person and virtual participation via WebEx.

Download the [Call for Presentations](#)

Confirmed Speakers at REPP:

Thermal Management of Hybrid Integrated Lasers in Si Photonics

David Coenen, imec



HALT and TC Reliability of QFN Assemblies with and without Urethane Coating

Reza Ghaffarian, NASA JPL



Mechanical Integrity of Hybrid Bonding

Oguzhan Orkut Okudur, imec



Reliability of Bonded Interface Materials for Power Electronics

Sreekant Narumanchi, Ph.D., National Renewable Energy Laboratory



Reliability Problems of Optoactive Materials in LED Packaging

Prof. Gabor Harsanyi, Budapest University of Technology and Economics



Cryogenic CMOS Technologies for Quantum Computing Systems

Alexander Grill, imec



Reliability Modeling of Electronics Cooling Systems in Data Centers

Srikanth Rangarajan, Binghamton Univ



Reliability and Availability of Novel Data Center Cooling Systems

Prof. Patrick McCluskey, University of Maryland



... and many more! See the [full listing](#)